# 8-Bit Addressable Latch 1-of-8 Decoder

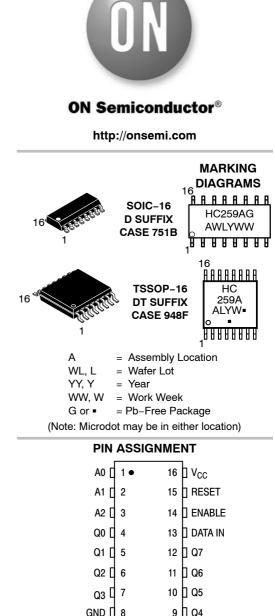
## High-Performance Silicon-Gate CMOS

The MC74HC259A is identical in pinout to the LS259. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

The HC259A has four modes of operation as shown in the mode selection table. In the addressable latch mode, the data on Data In is written into the addressed latch. The addressed latch follows the data input with all non-addressed latches remaining in their previous states. In the memory mode, all latches remain in their previous state and are unaffected by the Data or Address inputs. In the one-of-eight decoding or demultiplexing mode, the addressed output follows the state of Data In with all other outputs in the LOW state. In the Reset mode all outputs are LOW and unaffected by the address and data inputs. When operating the HC259A as an addressable latch, changing more than one bit of the address could impose a transient wrong address. Therefore, this should only be done while in the memory mode.

#### Features

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2 to 6 V
- Low Input Current: 1 μA
- High Noise Immunity Characteristic of CMOS Devices
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant



#### MODE SELECTION TABLE

Enable	Reset	Mode
L	Н	Addressable Latch
Н	Н	Memory
L	L	8-Line Demultiplexer
Н	L	Reset

#### ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

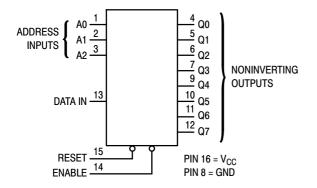


Figure 1. Logic Diagram

#### MAXIMUM RATINGS

#### Symbol Parameter Value Unit V<sub>CC</sub> DC Supply Voltage (Referenced to GND) -0.5 to +7.0 V DC Input Voltage (Referenced to GND) V Vin -0.5 to V<sub>CC</sub> + 0.5 -0.5 to V<sub>CC</sub> + 0.5 Vout DC Output Voltage (Referenced to GND) ٧ DC Input Current, per Pin ±20 mΑ l<sub>in</sub> DC Output Current, per Pin ±25 lout mΑ DC Supply Current, V<sub>CC</sub> and GND Pins ±50 mΑ I<sub>CC</sub> $\mathsf{P}_\mathsf{D}$ Power Dissipation in Still Air, SOIC Package 500 mW TSSOP Package 450 T<sub>stg</sub> Storage Temperature -65 to + 150 °C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter		Min	Max	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)		2.0	6.0	V
V <sub>in</sub> , V <sub>out</sub>	DC Input Voltage, Output Voltage (Referenced to GND)		0	V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature, All Package Types		-55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	(Figure 2) V <sub>CC</sub> = V <sub>CC</sub> =	= 2.0 V = 3.0 V = 4.5 V = 6.0 V	0 0 0 0	1000 600 500 400	ns

#### LATCH SELECTION TABLE

Address Inputs		uts	
A <sub>2</sub> A <sub>1</sub> A <sub>0</sub>		A <sub>0</sub>	Latch Addressed
	L L H L L H H		Q0 Q1 Q2 Q3 Q4 Q5 Q6 Q7

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range GND  $\leq (V_{in} \text{ or } V_{out}) \leq V_{CC}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or  $V_{CC}$ ). Unused outputs must be left open.

				Gu	aranteed Li	mit	
Symbol	Parameter	Test Conditions	V <sub>CC</sub> V	– 55 to 25°C	≤ <b>85°C</b>	≤ 125°C	Unit
V <sub>IH</sub>	Minimum High-Level Input Voltage	$\begin{array}{l} V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V} \\ \left I_{out}\right   \leq  20 \; \mu\text{A} \end{array}$	2.0 3.0 4.5 6.0	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	V
V <sub>IL</sub>	Maximum Low-Level Input Voltage	$\begin{array}{l} V_{out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V} \\ \left I_{out}\right   \leq  20 \; \mu\text{A} \end{array}$	2.0 3.0 4.5 6.0	0.5 0.9 1.35 1.80	0.5 0.9 1.35 1.80	0.5 0.9 1.35 1.80	V
V <sub>OH</sub>	Minimum High-Level Output Voltage		2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		$\label{eq:Vin} \begin{array}{ll} V_{in} = V_{IH} \text{ or } V_{IL} & \left  I_{out} \right  \leq 2.4 \text{ mA} \\ \left  I_{out} \right  \leq 4.0 \text{ mA} \\ \left  I_{out} \right  \leq 5.2 \text{ mA} \end{array}$	3.0 4.5 6.0	2.48 3.98 5.48	2.34 3.84 5.34	2.20 3.70 5.20	
V <sub>OL</sub>	Maximum Low-Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out}  \le 20 \ \mu A$	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		$ \begin{aligned} V_{in} = V_{IH} \text{ or } V_{IL} & \begin{array}{l}  I_{out}  \leq 2.4 \text{ mA} \\  I_{out}  \leq 4.0 \text{ mA} \\  I_{out}  \leq 5.2 \text{ mA} \end{aligned} $	3.0 4.5 6.0	0.26 0.26 0.26	0.33 0.33 0.33	0.40 0.40 0.40	
l <sub>in</sub>	Maximum Input Leakage Current	V <sub>in</sub> = V <sub>CC</sub> or GND	6.0	± 0.1	± 1.0	± 1.0	μA
I <sub>CC</sub>	Maximum Quiescent Supply Current (per Package)	$V_{in} = V_{CC} \text{ or } GND$ $I_{out} = 0 \ \mu A$	6.0	4	40	160	μA

### DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

			Guaranteed Limit			
Symbol	Parameter	V <sub>CC</sub> V	- 55 to 25°C	≤ <b>85</b> ° <b>C</b>	≤ 125°C	Unit
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Data to Output (Figures 2 and 7)	2.0 3.0 4.5 6.0	125 45 32 25	160 60 32 28	175 70 42 33	ns
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Address Select to Output (Figures 3 and 7)	2.0 3.0 4.5 6.0	150 60 32 28	175 70 40 30	200 80 45 35	ns
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay, Enable to Output (Figures 4 and 7)	2.0 3.0 4.5 6.0	150 60 32 28	175 70 40 30	200 80 45 35	ns
t <sub>PHL</sub>	Maximum Propagation Delay, Reset to Output (Figures 5 and 7)	2.0 3.0 4.5 6.0	110 36 22 19	125 45 26 23	160 60 32 28	ns
t <sub>TLH</sub> , t <sub>THL</sub>	Maximum Output Transition Time, Any Output (Figures 2 and 7)	2.0 3.0 4.5 6.0	75 27 15 13	95 32 19 16	110 36 22 19	ns
C <sub>in</sub>	Maximum Input Capacitance	_	10	10	10	pF

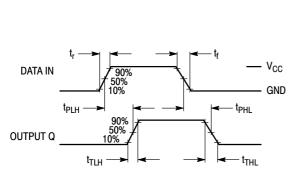
### **AC ELECTRICAL CHARACTERISTICS** ( $C_L = 50 \text{ pF}$ , Input $t_r = t_f = 6 \text{ ns}$ )

		Typical @ 25°C, V <sub>CC</sub> = 5.0 V	
C <sub>PD</sub>	Power Dissipation Capacitance (Per Package)	30	pF

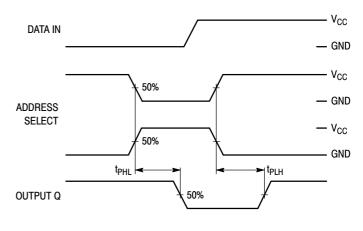
### **TIMING REQUIREMENTS** (Input $t_r = t_f = 6 \text{ ns}$ )

			Guaranteed Limit			
Symbol	Parameter	V <sub>CC</sub> V	- 55 to 25°C	≤ 85°C	≤ 125°C	Unit
t <sub>su</sub>	Minimum Setup Time, Address or Data to Enable (Figure 6)	2.0 3.0 4.5 6.0	75 30 15 13	95 40 19 16	110 55 22 19	ns
t <sub>h</sub>	Minimum Hold Time, Enable to Address or Data (Figure 6)	2.0 3.0 4.5 6.0	1 1 1	1 1 1	1 1 1	ns
t <sub>w</sub>	Minimum Pulse Width, Reset or Enable (Figure 4 or 5)	2.0 3.0 4.5 6.0	70 27 15 13	90 32 19 16	100 36 22 19	ns
t <sub>r</sub> , t <sub>f</sub>	Maximum Input Rise and Fall Times (Figure 2)	2.0 3.0 4.5 6.0	1000 800 500 400	1000 800 500 400	1000 800 500 400	ns

### SWITCHING WAVEFORMS









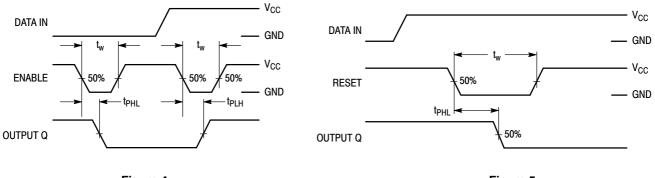
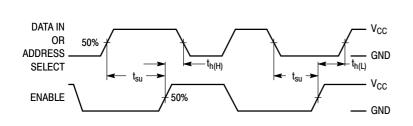
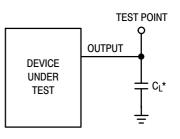


Figure 4.



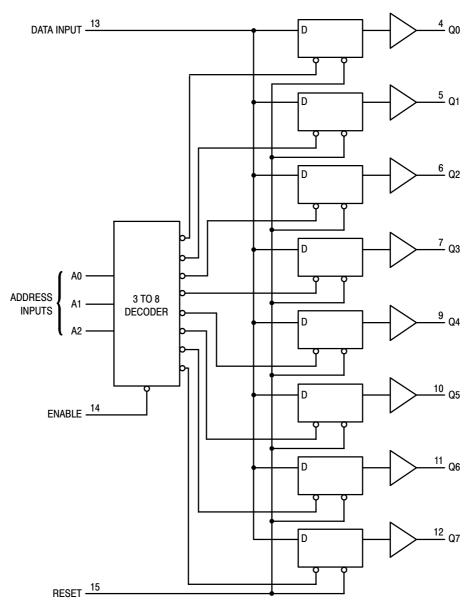


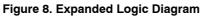


\*Includes all probe and jig capacitance

Figure 7. Test Circuit

Figure 6.





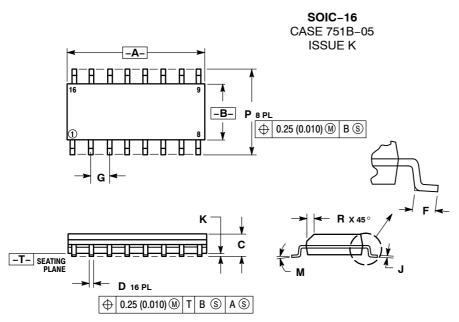
#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MC74HC259ADG	SOIC-16 (Pb-Free)	48 Units / Rail
MC74HC259ADR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
MC74HC259ADTR2G	TSSOP-16 (Pb-Free)	2500 / Tape & Reel
MC74HC259ADTG	TSSOP-16 (Pb-Free)	96 Units / Rail
NLVHC259ADR2G*	SOIC-16 (Pb-Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

### PACKAGE DIMENSIONS



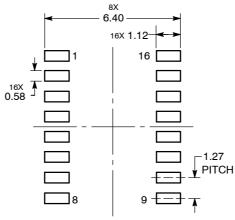
NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD DIDATELISION

4 5

DIMENSIONS A AND & DO NOT INCLUDE MOLD PROTRUSION. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
М	0 °	7°	0 °	7°
Р	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

**SOLDERING FOOTPRINT\*** 



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

MIN MAX

0.026 BSC

0.007 0.011

0.004 0.008

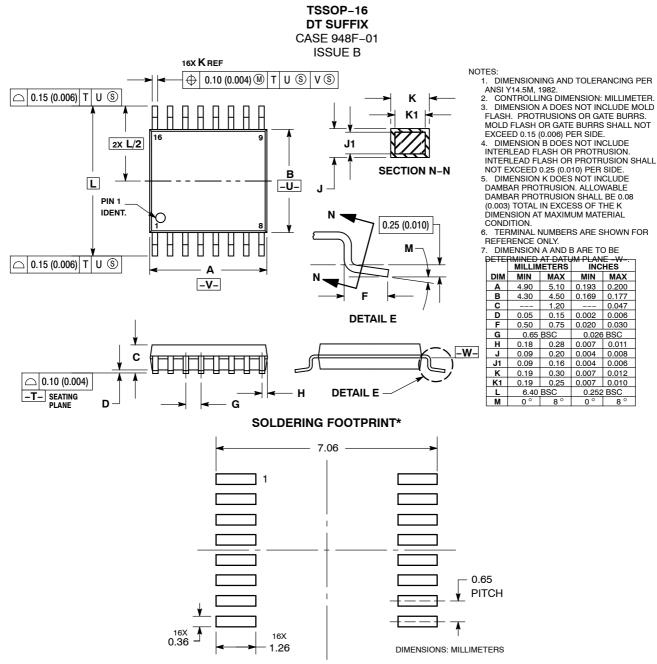
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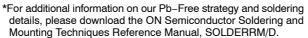
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